

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr> <td>Chih-Wei Lin</td> <td>12/31/2009</td> </tr> <tr> <td>Yi-Fang Lee</td> <td>05/11/2009</td> </tr> <tr> <td>Cheng-Ta Wu</td> <td>05/11/2009</td> </tr> <tr> <td>Cheng-Yuan Tsai</td> <td>05/11/2009</td> </tr> </tbody> </table>		Name	Execution Date	Chih-Wei Lin	12/31/2009	Yi-Fang Lee	05/11/2009	Cheng-Ta Wu	05/11/2009	Cheng-Yuan Tsai	05/11/2009		
Name	Execution Date												
Chih-Wei Lin	12/31/2009												
Yi-Fang Lee	05/11/2009												
Cheng-Ta Wu	05/11/2009												
Cheng-Yuan Tsai	05/11/2009												
RECEIVING PARTY DATA													
<table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 20%;">Name:</td> <td>Taiwan Semiconductor Manufacturing Company, Ltd.</td> </tr> <tr> <td>Street Address:</td> <td>No. 8, Li-Hsin Rd. 6</td> </tr> <tr> <td>Internal Address:</td> <td>Science-Based Industrial Park</td> </tr> <tr> <td>City:</td> <td>Hsin-Chu</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>300-77</td> </tr> </table>		Name:	Taiwan Semiconductor Manufacturing Company, Ltd.	Street Address:	No. 8, Li-Hsin Rd. 6	Internal Address:	Science-Based Industrial Park	City:	Hsin-Chu	State/Country:	TAIWAN	Postal Code:	300-77
Name:	Taiwan Semiconductor Manufacturing Company, Ltd.												
Street Address:	No. 8, Li-Hsin Rd. 6												
Internal Address:	Science-Based Industrial Park												
City:	Hsin-Chu												
State/Country:	TAIWAN												
Postal Code:	300-77												
PROPERTY NUMBERS Total: 1													
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 30%;">Property Type</th> <th style="width: 70%;">Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>12714194</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	12714194								
Property Type	Number												
Application Number:	12714194												
CORRESPONDENCE DATA													
<p>Fax Number: (972)732-9218</p> <p><i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 9727321001</p> <p>Email: gonzales@slater-matsil.com</p> <p>Correspondent Name: Steven H. Slater</p> <p>Address Line 1: 17950 Preston Road, Suite 1000</p> <p>Address Line 2: Slater & Matsil, L.L.P.</p> <p>Address Line 4: Dallas, TEXAS 75252</p>													
ATTORNEY DOCKET NUMBER:	TSM08-0807												
NAME OF SUBMITTER:	Della L. Gonzales												

CH \$40.00 12714194

501298260

PATENT
REEL: 025027 FRAME: 0811

Total Attachments: 2

source=TSM08-0807-Assignment#page1.tif

source=TSM08-0807-Assignment#page2.tif

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, the said application having been executed on the date set forth below; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. (TSMC), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C., is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said TSMC, its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said TSMC, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to TSMC, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said TSMC, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TSMC, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	Non-Volatile Memories and Methods of Fabrication Thereof			
SIGNATURE OF INVENTOR AND NAME	✓ Chih-Wei Lin	✓ <i>Yi-Fang Lee</i> Yi-Fang Lee 838	✓ <i>CTWu</i> Cheng-Ta Wu	✓ <i>Cheng-Yuan Tsai</i> Cheng-Yuan Tsai
DATE	✓	✓ 2009.05.11	✓ 2009.05.11	✓ 2009.05.11
RESIDENCE (City, County, State)	Taoyuan City, 330 Taiwan, R.O.C.	Taichung City, 403 Taiwan, R.O.C.	Shueishang Township, 608 Taiwan, R.O.C.	Chu-Pei City, Taiwan, R.O.C.

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, the said application having been executed on the date set forth below; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. (TSMC), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C., is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said TSMC, its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said TSMC, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to TSMC, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said TSMC, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TSMC, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	<i>Non-Volatile Memories and Methods of Fabrication Thereof</i>			
SIGNATURE OF INVENTOR AND NAME	林智偉 Chih-Wei Lin	Yi-Fang Lee	Cheng-Ta Wu	Cheng-Yuan Tsai
DATE	2009.12.31			
RESIDENCE (City, County, State)	Taoyuan City, 330 Taiwan, R.O.C.	Taichung City, 403 Taiwan, R.O.C.	Shueishang Township, 608 Taiwan, R.O.C.	Chu-Pei City, Taiwan, R.O.C.